

Welcome to [E-XFL.COM](#)

### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	LINbus, SIO, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	25
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212e2dfp-w4">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212e2dfp-w4</a>

## Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: “Standard”, “High Quality”, and “Specific”. The recommended applications for each Renesas Electronics product depends on the product’s quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as “Specific” without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as “Specific” or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is “Standard” unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.
  - “Standard”: Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.
  - “High Quality”: Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.
  - “Specific”: Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) “Renesas Electronics” as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) “Renesas Electronics product(s)” means any product developed or manufactured by or for Renesas Electronics.

## 1. Overview

### 1.1 Features

The R8C/2E Group and R8C/2F Group of single-chip MCUs incorporates the R8C/Tiny Series CPU core, employing sophisticated instructions for a high level of efficiency. With 1 Mbyte of address space, and it is capable of executing instructions at high speed. In addition, the CPU core boasts a multiplier for high-speed operation processing.

Power consumption is low, and the supported operating modes allow additional power control. These MCUs also use an anti-noise configuration to reduce emissions of electromagnetic noise and are designed to withstand EMI.

Integration of many peripheral functions, including multifunction timer and serial interface, reduces the number of system components.

Furthermore, the R8C/2F Group has on-chip data flash (1 KB  $\times$  2 blocks).

The difference between the R8C/2E Group and R8C/2F Group is only the presence or absence of data flash. Their peripheral functions are the same.

#### 1.1.1 Applications

Electronic household appliances, office equipment, audio equipment, consumer equipment, etc.

**Table 1.4 Specifications for R8C/2F Group (2)**

Item	Specification
Flash Memory	<ul style="list-style-type: none"> <li>• Programming and erasure voltage: VCC = 2.7 to 5.5 V</li> <li>• Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM)</li> <li>• Program security: ROM code protect, ID code check</li> <li>• Debug functions: On-chip debug, on-board flash rewrite function</li> </ul>
Operating Frequency/Supply Voltage	f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V), f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V)
Current consumption	Typ. 10 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 23 $\mu$ A (VCC = 3.0 V, wait mode (peripheral clock off)) Typ. 0.7 $\mu$ A (VCC = 3.0 V, stop mode)
Operating Ambient Temperature	-20 to 85°C (N version) -40 to 85°C (D version) <sup>(1)</sup>
Package	32-pin LQFP Package code: PLQP0032GB-A (previous code: 32P6U-A)

**NOTE:**

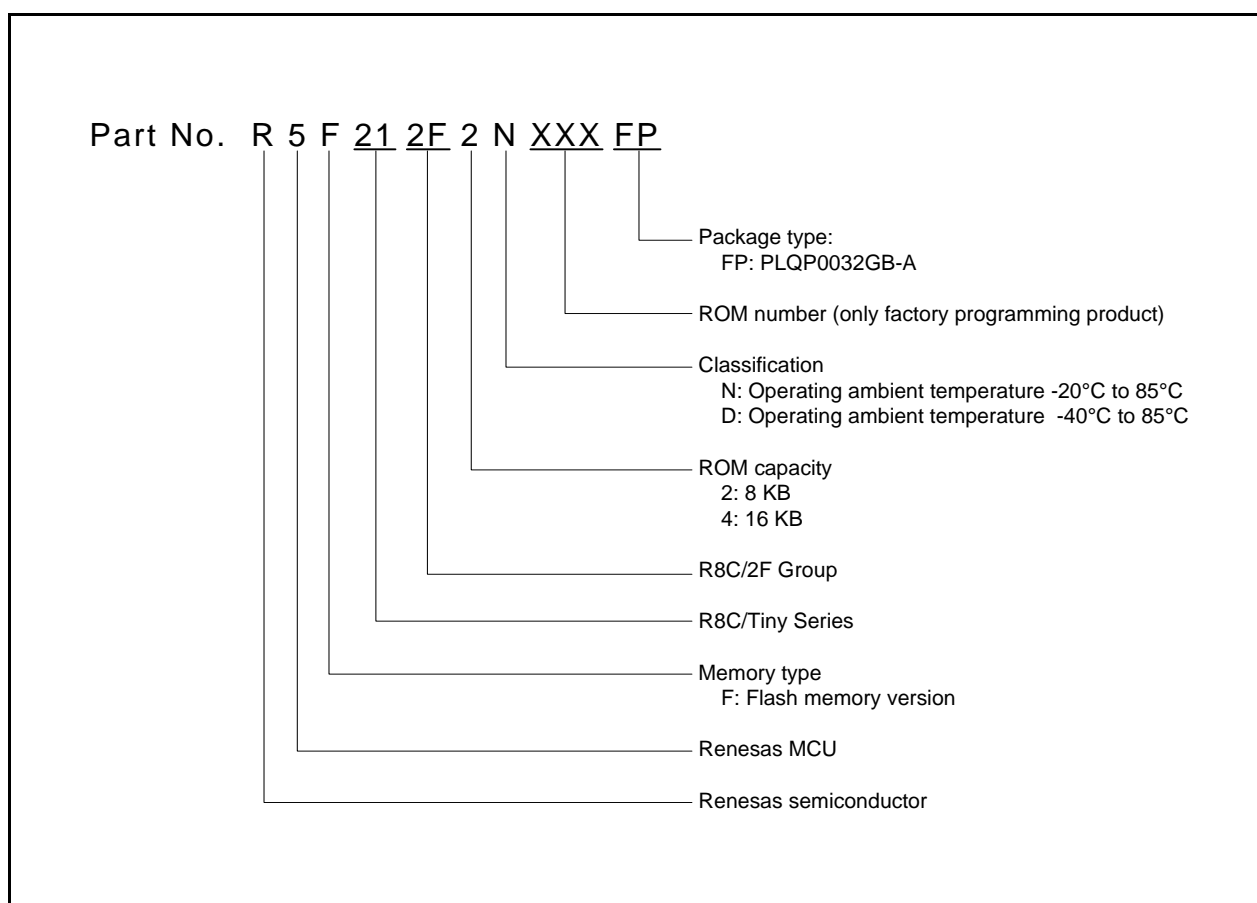
1. Specify the D version if D version functions are to be used.

**Table 1.6 Product List for R8C/2F Group****Current of Dec. 2007**

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F212F2NFP	8 Kbytes	1 Kbyte × 2	512 bytes	PLQP0032GB-A	N version
R5F212F4NFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0032GB-A	
R5F212F2DFP	8 Kbytes	1 Kbyte × 2	512 bytes	PLQP0032GB-A	D version
R5F212F4DFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0032GB-A	
R5F212F2NXXXFP	8 Kbytes	1 Kbyte × 2	512 bytes	PLQP0032GB-A	N version
R5F212F4NXXXFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0032GB-A	Factory programming product <sup>(1)</sup>
R5F212F2DXXXFP	8 Kbytes	1 Kbyte × 2	512 bytes	PLQP0032GB-A	D version
R5F212F4DXXXFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0032GB-A	Factory programming product <sup>(1)</sup>

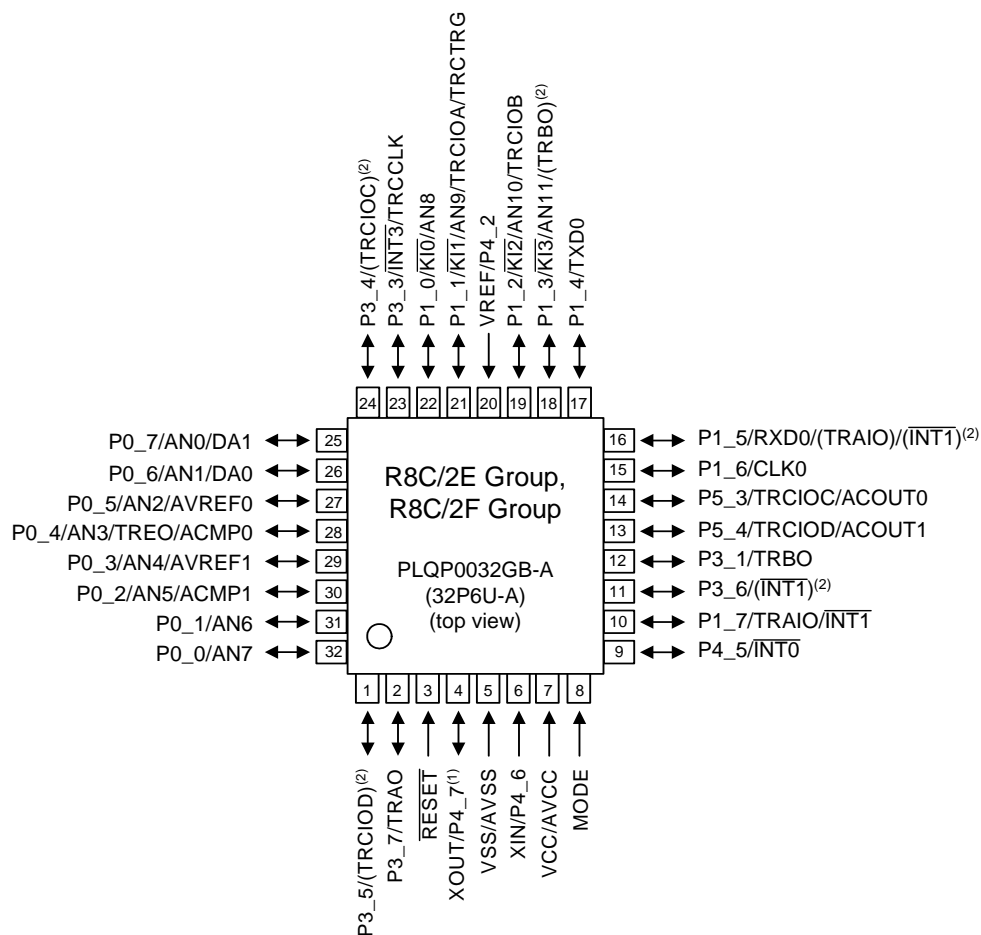
NOTE:

1. The user ROM is programmed before shipment.

**Figure 1.2 Part Number, Memory Size, and Package of R8C/2F Group**

## 1.4 Pin Assignment

Figure 1.4 shows Pin Assignments (Top View). Table 1.7 outlines the Pin Name Information by Pin Number.



### NOTES:

1. P4\_7 is an input-only port.
2. Can be assigned to the pin in parentheses by a program.
3. Confirm the pin 1 position on the package by referring to the package dimensions.

**Figure 1.4 Pin Assignments (Top View)**

## 1.5 Pin Functions

Table 1.8 list Pin Functions.

**Table 1.8 Pin Functions**

Type	Symbol	I/O Type	Description
Power supply input	VCC, VSS	I	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	I	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	RESET	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. <sup>(1)</sup> To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
INT interrupt input	INT0, INT1, INT3	I	INT interrupt input pins
Key input interrupt	KI0 to KI3	I	Key input interrupt input pins
Timer RA	TRAO	O	Timer RA output pin
	TRAIO	I/O	Timer RA I/O pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIO, TRCIOD	I/O	Sharing output-compare output / input-capture input / PWM / PWM2 output pins
Timer RE	TREO	O	Timer RE output pin
Serial interface	CLK0	I/O	Clock I/O pin
	RXD0	I	Receive data input pin
	TXD0	O	Transmit data output pin
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
D/A converter	DA0 to DA1	O	Output pins from D/A converter
Comparator	AVREF0 to AVREF1	I	Reference voltage input pins to comparator
	ACMP0 to ACMP1	I	Analog voltage input pins to comparator
	ACOUT0 to ACOUT1	O	Comparison result output pins of comparator
I/O port	P0_0 to P0_7, P1_0 to P1_7, P3_1, P3_3 to P3_7, P4_5, P5_3, P5_4	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. P1_0 to P1_7 also function as LED drive ports.
Input port	P4_2, P4_6, P4_7	I	Input-only ports

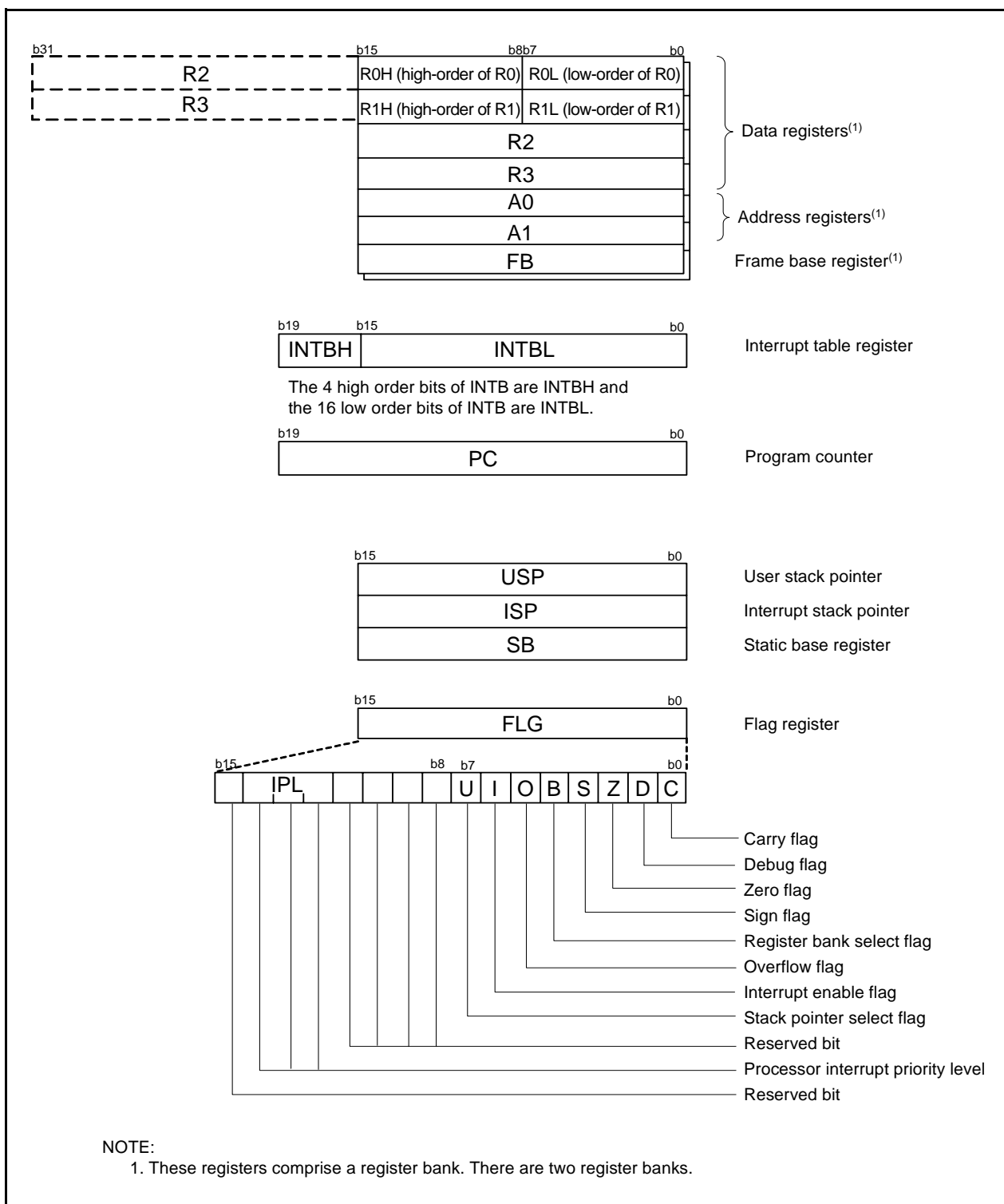
I: Input      O: Output      I/O: Input and output

NOTE:

1. Refer to the oscillator manufacturer for oscillation characteristics.

## 2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.



**Figure 2.1 CPU Registers**

### 3. Memory

#### 3.1 R8C/2E Group

Figure 3.1 is a Memory Map of R8C/2E Group. The R8C/2E group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM area is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses beginning with address 00400h. For example, a 1-Kbyte internal RAM area is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

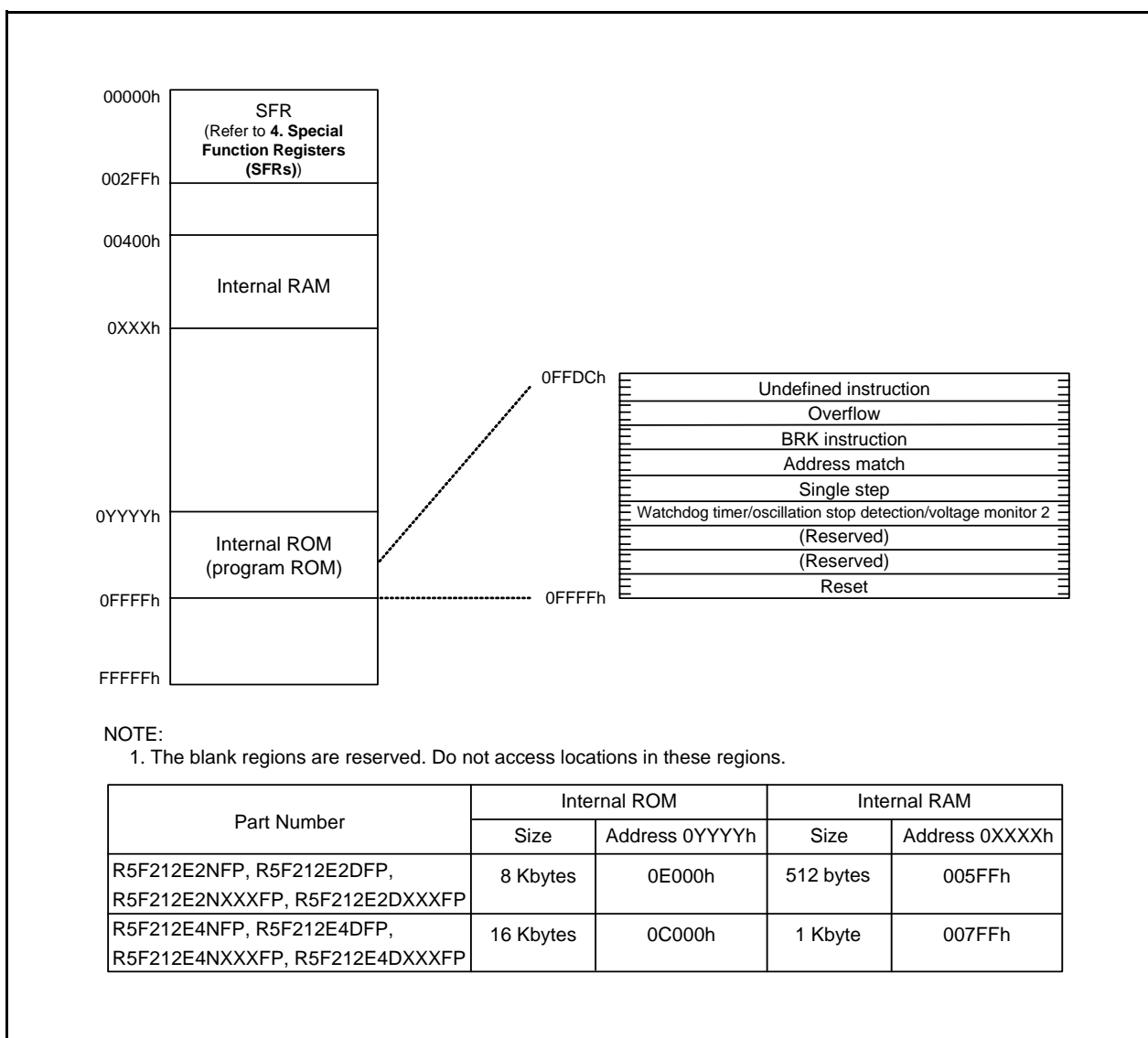


Figure 3.1 Memory Map of R8C/2E Group

### 3.2 R8C/2F Group

Figure 3.2 is a Memory Map of R8C/2F Group. The R8C/2F group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

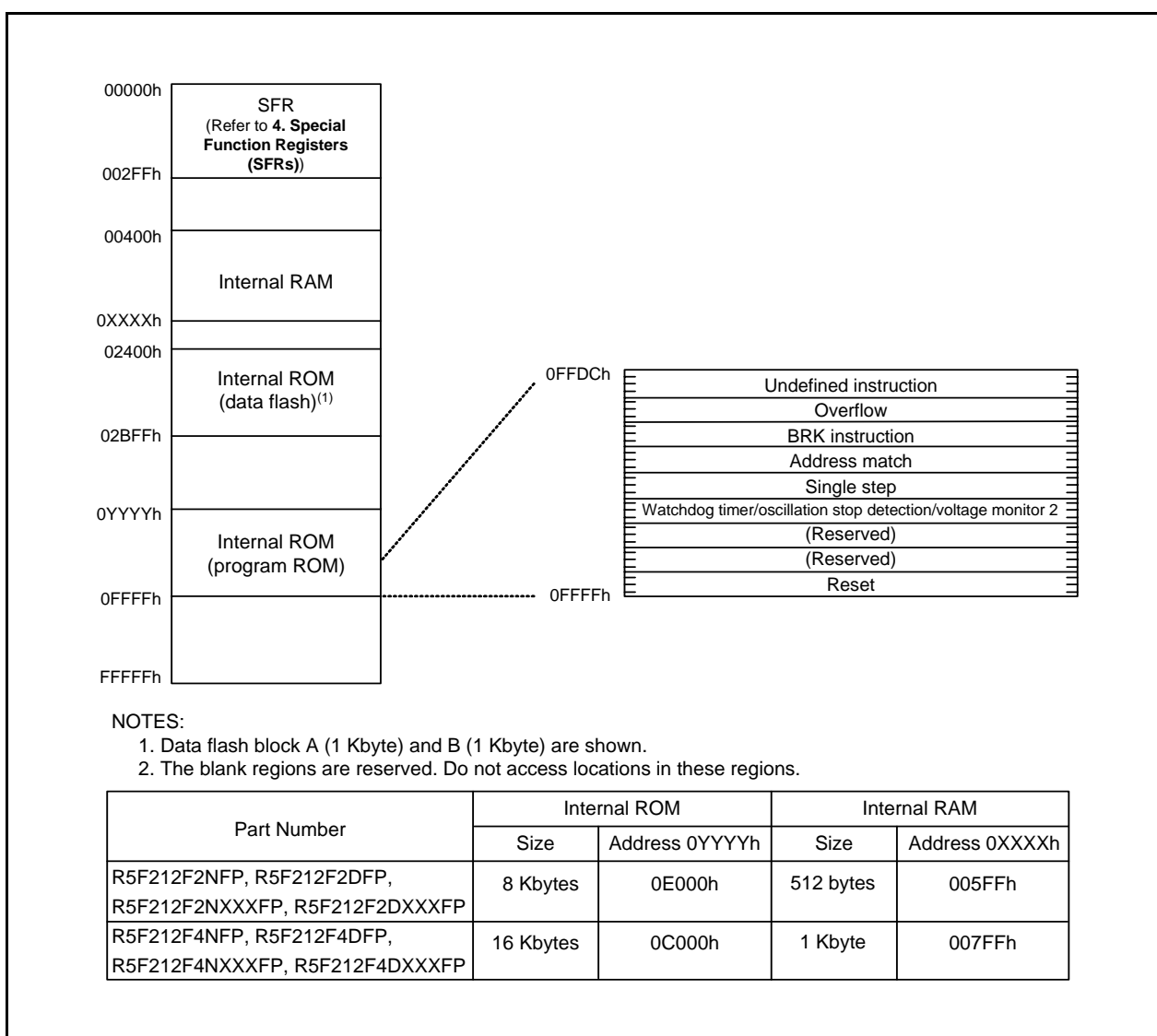
The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM area is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM area is allocated higher addresses, beginning with address 00400h. For example, a 1-Kbyte internal RAM is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.



**Figure 3.2 Memory Map of R8C/2F Group**

## 4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.7 list the special function registers.

**Table 4.1 SFR Information (1)(1)**

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h			
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			00h
0013h	Address Match Interrupt Enable Register	AIER	00h
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			00h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b(4)
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h			
0027h			
0028h			
0029h			
002Ah			
002Bh			
002Ch	High-Speed On-Chip Oscillator Control Register 7	FRA7	When Shipping
0030h			
0031h	Voltage Detection Register 1 (2)	VCA1	00001000b
0032h	Voltage Detection Register 2 (2)	VCA2	00100000b
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register(3)	VW1C	00001000b
0037h	Voltage Monitor 2 Circuit Control Register(3)	VW2C	00h
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

**NOTES:**

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, and voltage monitor 1 reset or voltage monitor 2 reset do not affect this register.
3. Software reset, watchdog timer reset, and voltage monitor 1 reset or voltage monitor 2 reset do not affect b2 and b3.
4. The CSPROINI bit in the OFS register is set to 0.

**Table 4.2 SFR Information (2)<sup>(1)</sup>**

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h			
0049h			
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh			
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h			
0054h			
0055h			
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh	Comparator 0 Interrupt Control Register	CM0IC	XXXXX000b
005Ch	Comparator 1 Interrupt Control Register	CM1IC	XXXXX000b
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

**Table 4.3 SFR Information (3)<sup>(1)</sup>**

Address	Register	Symbol	After reset
0080h			
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h			
0089h			
008Ah			
008Bh			
008Ch			
008Dh			
008Eh			
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h			
00A9h			
00AAh			
00ABh			
00ACh			
00ADh			
00AEh			
00AFh			
00B0h			
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh			
00BCh			
00BDh			
00BEh			
00BFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

**Table 4.4 SFR Information (4)<sup>(1)</sup>**

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A Register 0	DA0	00h
00D9h			
00DAh	D/A Register 1	DA1	00h
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	00h
00E1h	Port P1 Register	P1	00h
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h			
00E5h	Port P3 Register	P3	00h
00E6h			
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	00h
00E9h	Port P5 Register	P5	00h
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h	Pin Select Register 2	PINSR2	00h
00F7h	Pin Select Register 3	PINSR3	00h
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	00h
00FEh	Port P1 Drive Capacity Control Register	P1DRR	00h
00FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

**Table 4.6 SFR Information (6)<sup>(1)</sup>**

Address	Register	Symbol	After reset
0140h			
0141h			
0142h			
0143h			
0144h			
0145h			
0146h			
0147h			
0148h			
0149h			
014Ah			
014Bh			
014Ch			
014Dh			
014Eh			
014Fh			
0150h			
0151h			
0152h			
0153h			
0154h			
0155h			
0156h			
0157h			
0158h			
0159h			
015Ah			
015Bh			
015Ch			
015Dh			
015Eh			
015Fh			
0160h			
0161h			
0162h			
0163h			
0164h			
0165h			
0166h			
0167h			
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h	Comparator 0 Control Register	ACCR0	00001000b
0175h	Comparator 1 Control Register	ACCR1	00001000b
0176h			
0177h	Comparator Mode Register	ACMR	00h
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

NOTE:

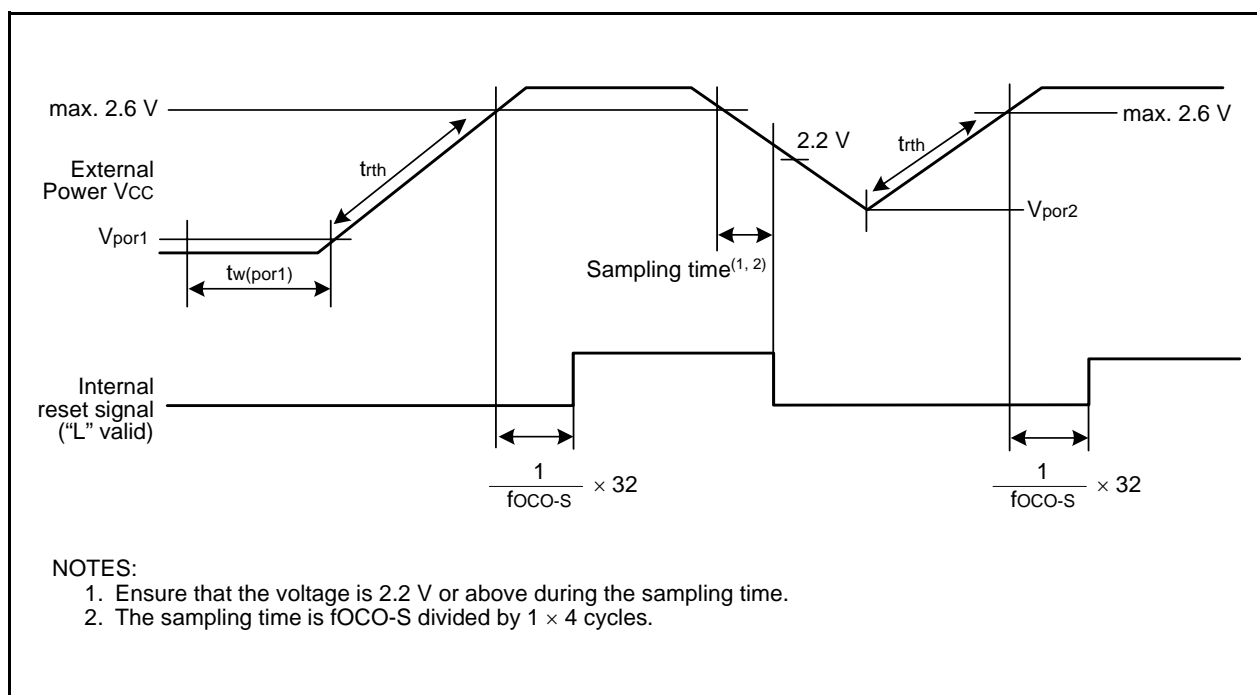
1. The blank regions are reserved. Do not access locations in these regions.

**Table 5.10 Power-on Reset Circuit, Voltage Monitor 0 Reset Electrical Characteristics**

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V <sub>por1</sub>	Power-on reset valid voltage <sup>(3)</sup>		–	–	0.1	V
V <sub>por2</sub>	Power-on reset valid voltage		0	–	2.6	V
tr <sub>th</sub>	External power V <sub>CC</sub> rise gradient <sup>(2)</sup>		20	–	–	mV/msec

**NOTES:**

1. The measurement condition is T<sub>opr</sub> = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. This condition (external power V<sub>CC</sub> rise gradient) does not apply if V<sub>CC</sub> ≥ 1.0 V.
3. t<sub>w(por1)</sub> indicates the duration the external power V<sub>CC</sub> must be held below the effective voltage (V<sub>por1</sub>) to enable a power on reset. When turning on the power for the first time, maintain t<sub>w(por1)</sub> for 30 s or more if –20°C ≤ T<sub>opr</sub> ≤ 85°C, maintain t<sub>w(por1)</sub> for 3,000 s or more if –40°C ≤ T<sub>opr</sub> < –20°C.

**Figure 5.3 Reset Circuit Electrical Characteristics**

**Table 5.14 Electrical Characteristics (1) [V<sub>CC</sub> = 5 V]**

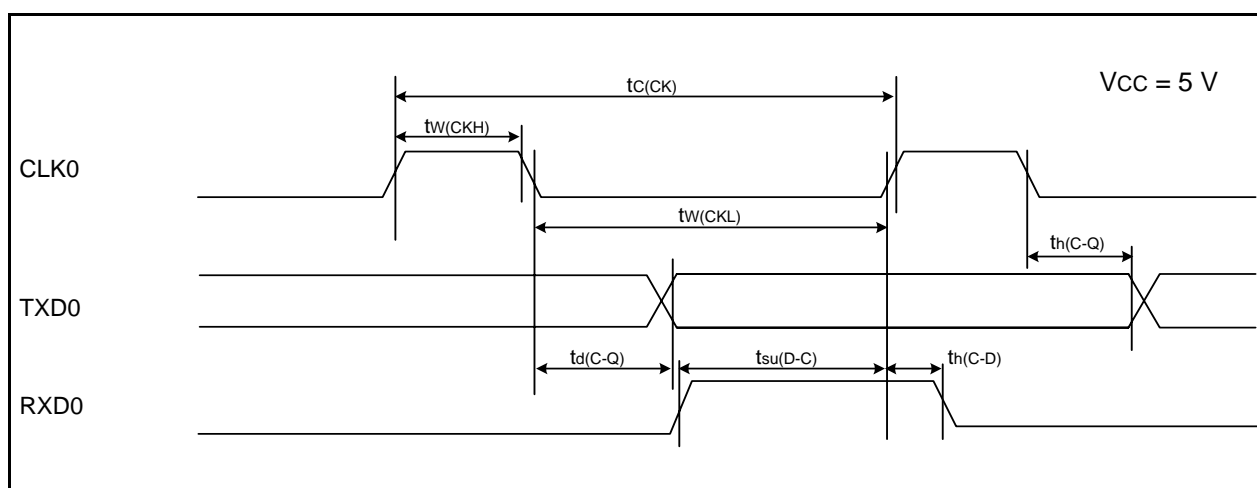
Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V <sub>OH</sub>	Output "H" voltage	Except P1_0 to P1_7, XOUT	I <sub>OH</sub> = -5 mA	V <sub>CC</sub> - 2.0	—	V <sub>CC</sub>	V
			I <sub>OH</sub> = -200 μA	V <sub>CC</sub> - 0.5	—	V <sub>CC</sub>	V
		P1_0 to P1_7	Drive capacity HIGH I <sub>OH</sub> = -10 mA	V <sub>CC</sub> - 2.0	—	V <sub>CC</sub>	V
			Drive capacity LOW I <sub>OH</sub> = -5 mA	V <sub>CC</sub> - 2.0	—	V <sub>CC</sub>	V
		XOUT	Drive capacity HIGH I <sub>OH</sub> = -1 mA	V <sub>CC</sub> - 2.0	—	V <sub>CC</sub>	V
			Drive capacity LOW I <sub>OH</sub> = -500 μA	V <sub>CC</sub> - 2.0	—	V <sub>CC</sub>	V
V <sub>OL</sub>	Output "L" voltage	Except P1_0 to P1_7, XOUT	I <sub>OL</sub> = 5 mA	—	—	2.0	V
			I <sub>OL</sub> = 200 μA	—	—	0.45	V
		P1_0 to P1_7	Drive capacity HIGH I <sub>OL</sub> = 10 mA	—	—	2.0	V
			Drive capacity LOW I <sub>OL</sub> = 5 mA	—	—	2.0	V
		XOUT	Drive capacity HIGH I <sub>OL</sub> = 1 mA	—	—	2.0	V
			Drive capacity LOW I <sub>OL</sub> = 500 μA	—	—	2.0	V
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis	<u>INT0</u> , <u>INT1</u> , <u>INT3</u> , <u>KI0</u> , <u>KI1</u> , <u>KI2</u> , <u>KI3</u> , <u>TRAIO</u> , <u>RXD0</u> , <u>CLK0</u>		0.1	0.5	—	V
		<u>RESET</u>		0.1	1.0	—	V
I <sub>IH</sub>	Input "H" current		V <sub>I</sub> = 5 V, V <sub>CC</sub> = 5 V	—	—	5.0	μA
I <sub>IL</sub>	Input "L" current		V <sub>I</sub> = 0 V, V <sub>CC</sub> = 5 V	—	—	-5.0	μA
R <sub>PULLUP</sub>	Pull-up resistance		V <sub>I</sub> = 0 V, V <sub>CC</sub> = 5 V	30	50	167	kΩ
R <sub>FXIN</sub>	Feedback resistance	XIN		—	1.0	—	MΩ
V <sub>RAM</sub>	RAM hold voltage		During stop mode	1.8	—	—	V

## NOTE:

- V<sub>CC</sub> = 4.2 to 5.5 V at T<sub>opr</sub> = -20 to 85°C (N version) / -40 to 85°C (D version), f<sub>(XIN)</sub> = 20 MHz, unless otherwise specified.

**Table 5.18 Serial Interface**

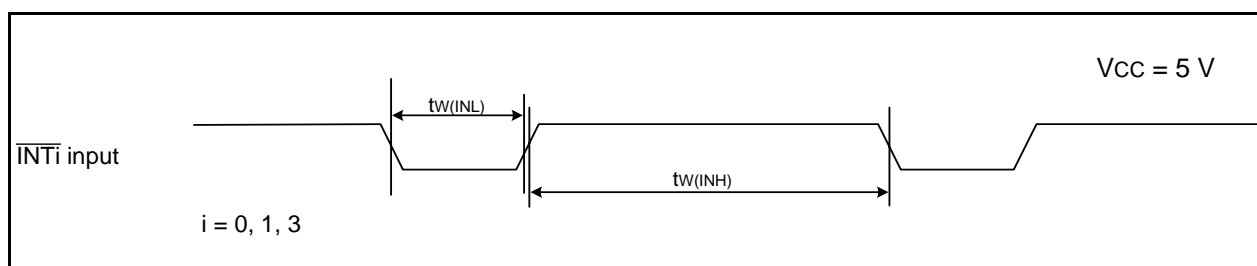
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	200	—	ns
$t_{w(CKH)}$	CLK0 input "H" width	100	—	ns
$t_{w(CKL)}$	CLK0 input "L" width	100	—	ns
$t_{d(C-Q)}$	TXD0 output delay time	—	50	ns
$t_{h(C-Q)}$	TXD0 hold time	0	—	ns
$t_{su(D-C)}$	RXD0 input setup time	50	—	ns
$t_{h(C-D)}$	RXD0 input hold time	90	—	ns

**Figure 5.6 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.19 External Interrupt  $\overline{INTi}$  ( $i = 0, 1, 3$ ) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input "H" width	250 <sup>(1)</sup>	—	ns
$t_{w(INL)}$	$\overline{INTi}$ input "L" width	250 <sup>(2)</sup>	—	ns

**NOTES:**

1. When selecting the digital filter by the  $\overline{INTi}$  input filter select bit, use an  $\overline{INTi}$  input HIGH width of either (1/digital filter clock frequency  $\times 3$ ) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the  $\overline{INTi}$  input filter select bit, use an  $\overline{INTi}$  input LOW width of either (1/digital filter clock frequency  $\times 3$ ) or the minimum value of standard, whichever is greater.

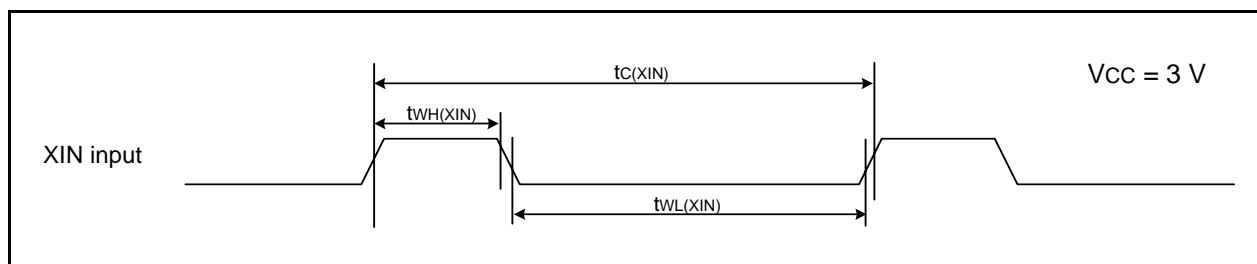
**Figure 5.7 External Interrupt  $\overline{INTi}$  Input Timing Diagram when Vcc = 5 V**

**Table 5.21 Electrical Characteristics (4) [ $V_{CC} = 3\text{ V}$ ]**  
**( $T_{opr} = -20$  to  $85^{\circ}\text{C}$  (N version) /  $-40$  to  $85^{\circ}\text{C}$  (D version), unless otherwise specified.)**

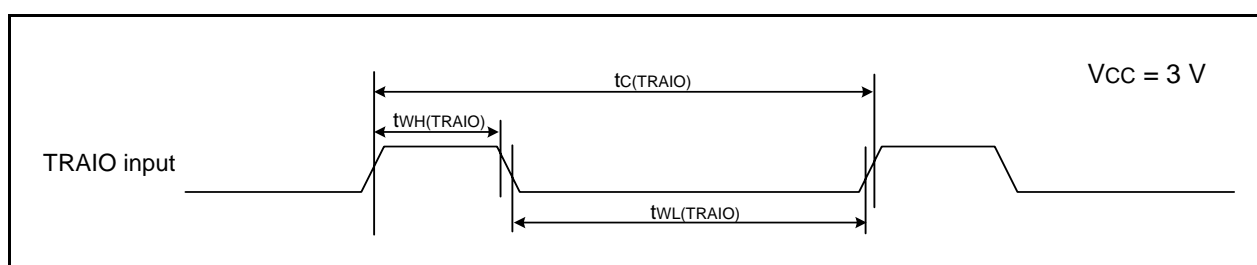
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$I_{CC}$	Power supply current ( $V_{CC} = 2.7$ to $3.3\text{ V}$ ) Single-chip mode, output pins are open, other pins are $V_{SS}$	High-speed clock mode	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division			mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8			mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division			mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8			mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1			$\mu\text{A}$
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0 VCA20 = 1			$\mu\text{A}$
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0 VCA20 = 1			$\mu\text{A}$
		Stop mode	XIN clock off, $T_{opr} = 25^{\circ}\text{C}$ High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0			$\mu\text{A}$
			XIN clock off, $T_{opr} = 85^{\circ}\text{C}$ High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0			$\mu\text{A}$

**Timing requirements****(Unless Otherwise Specified:  $V_{CC} = 3\text{ V}$ ,  $V_{SS} = 0\text{ V}$  at  $T_{opr} = 25^{\circ}\text{C}$ ) [ $V_{CC} = 3\text{ V}$ ]****Table 5.22 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input "H" width	40	–	ns
$t_{WL(XIN)}$	XIN input "L" width	40	–	ns

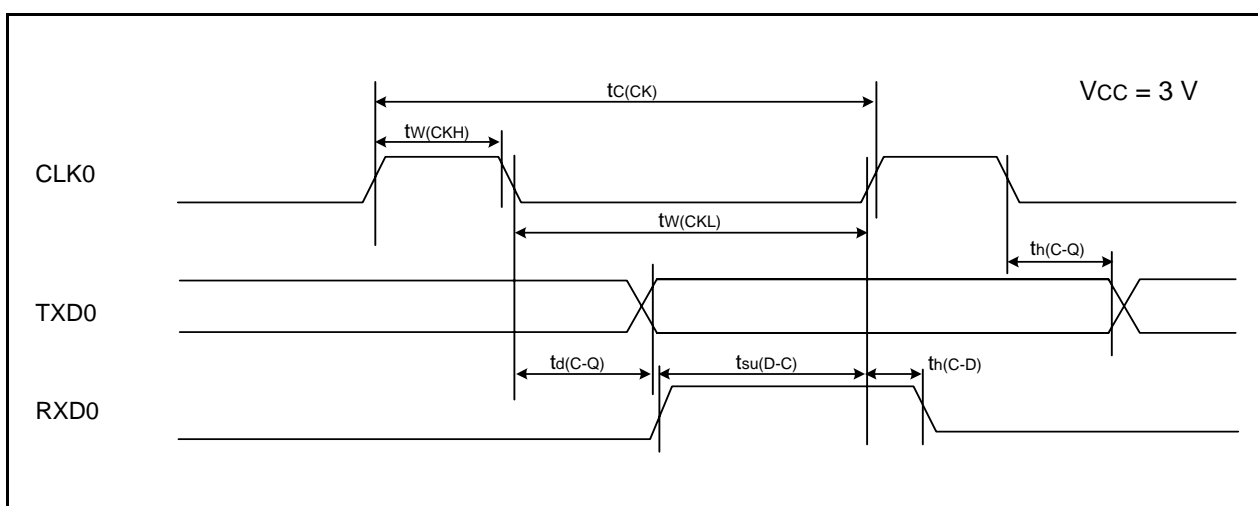
**Figure 5.8 XIN Input Timing Diagram when  $V_{CC} = 3\text{ V}$** **Table 5.23 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	120	–	ns

**Figure 5.9 TRAIO Input Timing Diagram when  $V_{CC} = 3\text{ V}$**

**Table 5.24 Serial Interface**

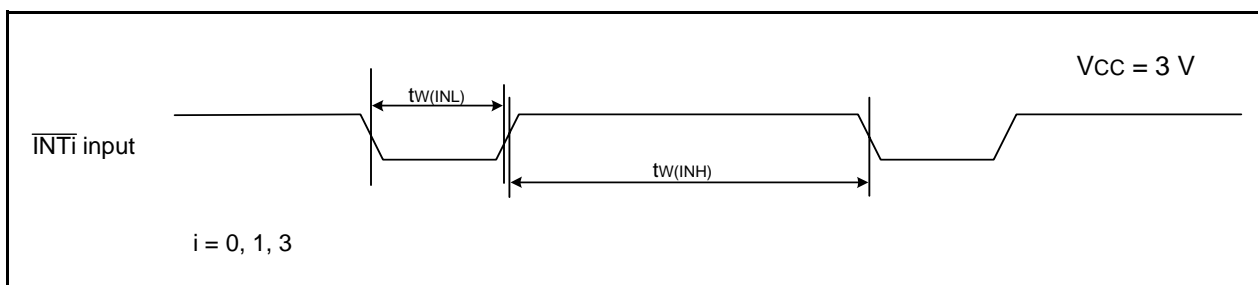
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	300	—	ns
$t_{w(CKH)}$	CLK0 input “H” width	150	—	ns
$t_{w(CKL)}$	CLK0 Input “L” width	150	—	ns
$t_{d(C-Q)}$	TXD0 output delay time	—	80	ns
$t_{h(C-Q)}$	TXD0 hold time	0	—	ns
$t_{su(D-C)}$	RXD0 input setup time	70	—	ns
$t_{h(C-D)}$	RXD0 input hold time	90	—	ns

**Figure 5.10 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.25 External Interrupt  $\overline{INTi}$  ( $i = 0, 1, 3$ ) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input “H” width	380 <sup>(1)</sup>	—	ns
$t_{w(INL)}$	$\overline{INTi}$ input “L” width	380 <sup>(2)</sup>	—	ns

**NOTES:**

- When selecting the digital filter by the  $\overline{INTi}$  input filter select bit, use an  $\overline{INTi}$  input HIGH width of either (1/digital filter clock frequency  $\times$  3) or the minimum value of standard, whichever is greater.
- When selecting the digital filter by the  $\overline{INTi}$  input filter select bit, use an  $\overline{INTi}$  input LOW width of either (1/digital filter clock frequency  $\times$  3) or the minimum value of standard, whichever is greater.

**Figure 5.11 External Interrupt  $\overline{INTi}$  Input Timing Diagram when Vcc = 3 V**